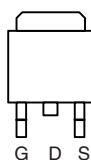


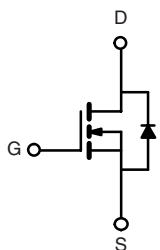
# Automotive N-Channel 40 V (D-S) 175 °C MOSFET

## PRODUCT SUMMARY

$V_{DS}$ (V)	40
$R_{DS(on)}$ ( $\Omega$ ) at $V_{GS} = 10$ V	0.0035
$R_{DS(on)}$ ( $\Omega$ ) at $V_{GS} = 4.5$ V	-
$I_D$ (A)	120
Configuration	Single

**TO-263**


Top View



N-Channel MOSFET

## FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- Package with Low Thermal Resistance
- AEC-Q101 Qualified<sup>d</sup>
- Compliant to RoHS Directive 2002/95/EC
- Find out more about Vishay's Automotive Grade Product Requirements at: [www.vishay.com/applications](http://www.vishay.com/applications)



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

**AUTOMOTIVE**  
GRADE

## ORDERING INFORMATION

Package	TO-263
Lead (Pb)-free and Halogen-free	SQM110N04-04-GE3

## ABSOLUTE MAXIMUM RATINGS $T_C = 25$ °C, unless otherwise noted

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	$V_{DS}$	40	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	
Continuous Drain Current <sup>a</sup>	$I_D$	$T_C = 25$ °C	A
		$T_C = 125$ °C	
Continuous Source Current (Diode Conduction) <sup>a</sup>	$I_S$	120	
Pulsed Drain Current <sup>b</sup>	$I_{DM}$	350	
Single Pulse Avalanche Energy	$E_{AS}$	180	mJ
Single Pulse Avalanche Current		60	A
Maximum Power Dissipation <sup>b</sup>	$P_D$	$T_C = 25$ °C	W
		$T_A = 25$ °C	
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	- 55 to + 175	°C

## THERMAL RESISTANCE RATINGS

PARAMETER	SYMBOL	LIMIT	UNIT
Junction-to-Ambient	$R_{thJA}$	40	°C/W
Junction-to-Case (Drain)	$R_{thJC}$	0.6	

### Notes

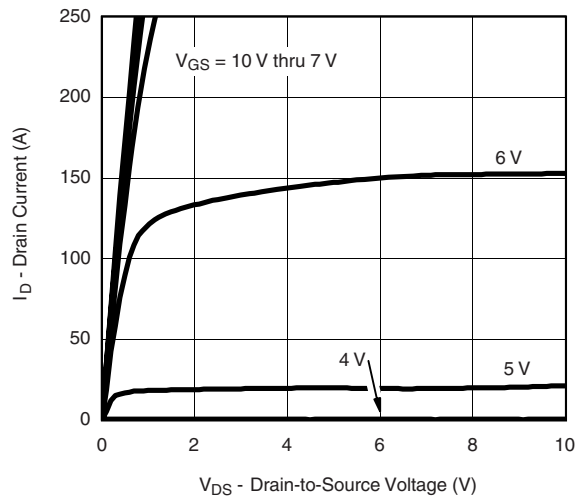
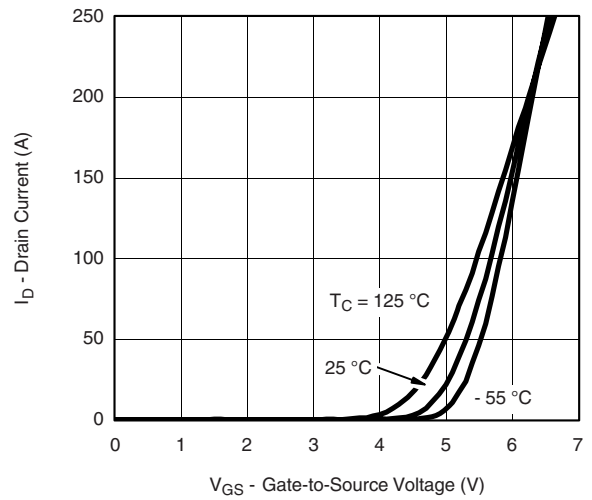
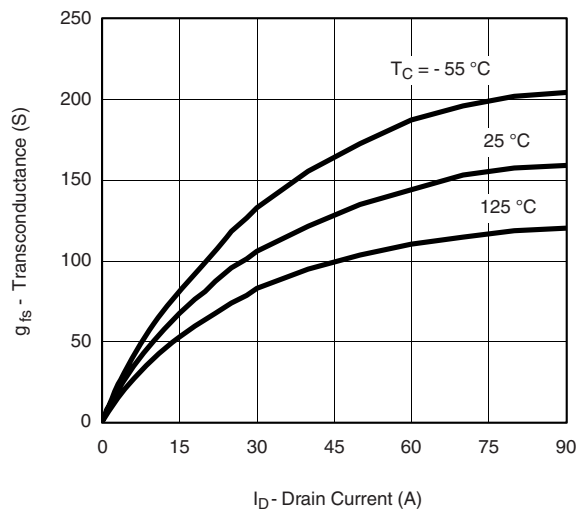
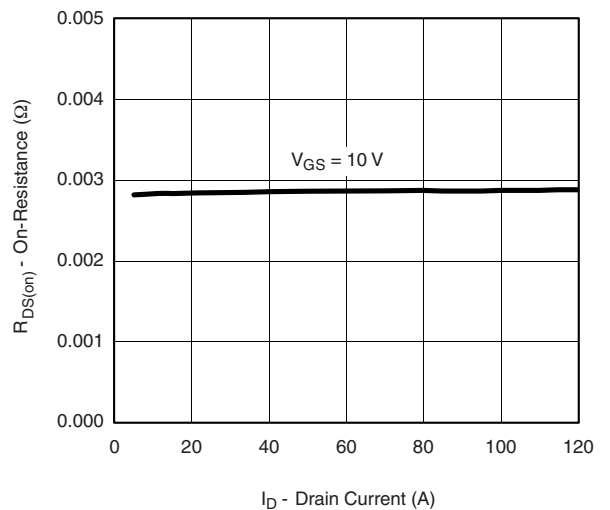
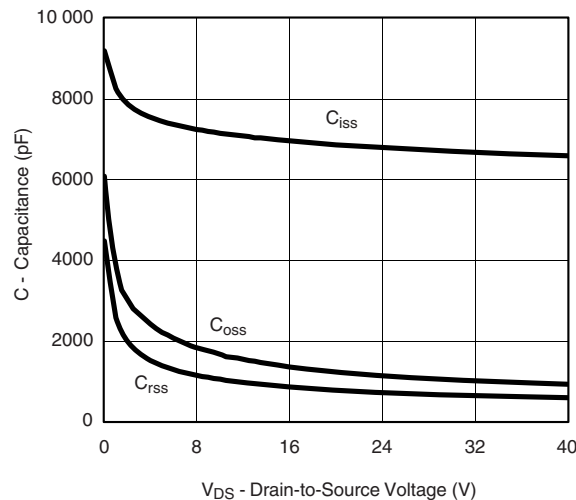
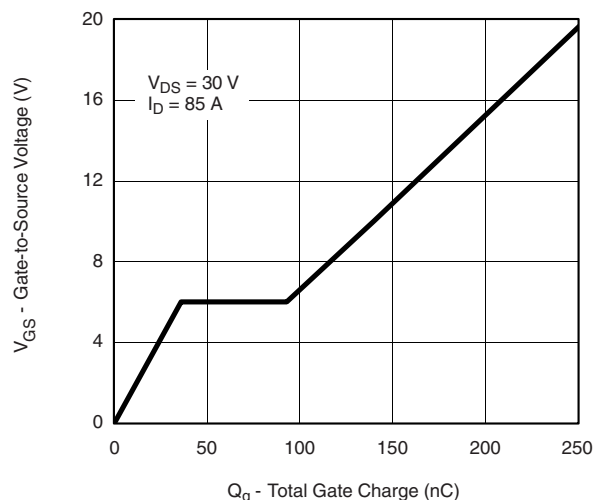
- Package limited.
- Pulse test; pulse width  $\leq 300$   $\mu$ s, duty cycle  $\leq 2$  %.
- When mounted on 1" square PCB (FR-4 material).
- Parametric verification ongoing.

SPECIFICATIONS T <sub>C</sub> = 25 °C, unless otherwise noted							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA		40	-	-	V
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA		2.5	-	3.5	
Gate-Source Leakage	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ± 20 V		-	-	± 100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 40 V	-	-	1.0	μA
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 40 V, T <sub>J</sub> = 125 °C	-	-	50	
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 40 V, T <sub>J</sub> = 175 °C	-	-	250	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = 10 V	V <sub>DS</sub> ≥ 5 V	110	-	-	A
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 30 A	-	0.0028	0.0035	Ω
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 30 A, T <sub>J</sub> = 125 °C	-	-	0.0055	
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 30 A, T <sub>J</sub> = 175 °C	-	-	0.0060	
		V <sub>GS</sub> = 4.5 V	I <sub>D</sub> = 20 A	-	-	-	
Forward Transconductance <sup>a</sup>	g <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 30 A		30	-	-	S
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 25 V, f = 1 MHz	-	6800	-	pF
Output Capacitance	C <sub>oss</sub>			-	1110	-	
Reverse Transfer Capacitance	C <sub>rss</sub>			-	690	-	
Total Gate Charge <sup>c</sup>	Q <sub>g</sub>	V <sub>GS</sub> = 10 V	V <sub>DS</sub> = 30 V, I <sub>D</sub> = 110 A	-	140	-	nC
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>			-	35	-	
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			-	55	-	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>	V <sub>DD</sub> = 30 V, R <sub>L</sub> = 0.47 Ω I <sub>D</sub> ≡ 110 A, V <sub>GEN</sub> = 10 V, R <sub>g</sub> = 2.5 Ω		-	20	-	ns
Rise Time <sup>c</sup>	t <sub>r</sub>			-	115	-	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			-	75	-	
Fall Time <sup>c</sup>	t <sub>f</sub>			-	85	-	
Source-Drain Diode Ratings and Characteristics T <sub>C</sub> = 25 °C <sup>b</sup>							
Pulsed Current <sup>a</sup>	I <sub>SM</sub>			-	-	350	A
Forward Voltage	V <sub>SD</sub>	I <sub>F</sub> = 110 A, V <sub>GS</sub> = 0 V		-	1.1	1.4	V

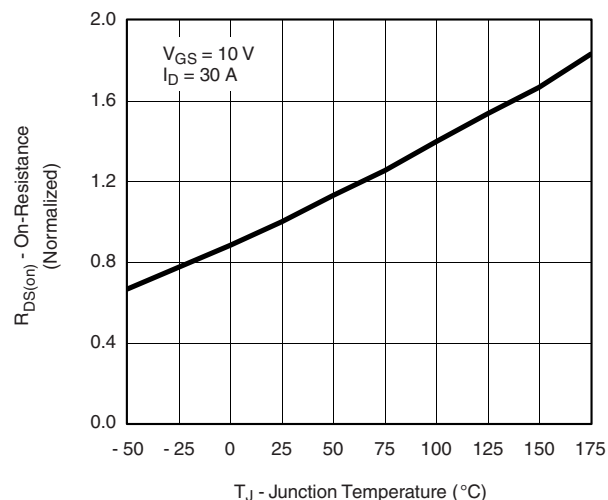
**Notes**

- a. Pulse test; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$ .  
b. Guaranteed by design, not subject to production testing.  
c. Independent of operating temperature.

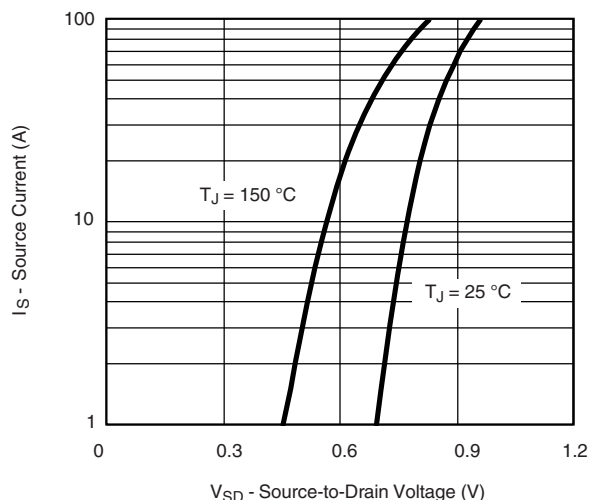
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**TYPICAL CHARACTERISTICS**  $T_A = 25\text{ }^{\circ}\text{C}$ , unless otherwise noted

**Output Characteristics**

**Transfer Characteristics**

**Transconductance**

**On-Resistance vs. Drain Current**

**Capacitance**

**Gate Charge**

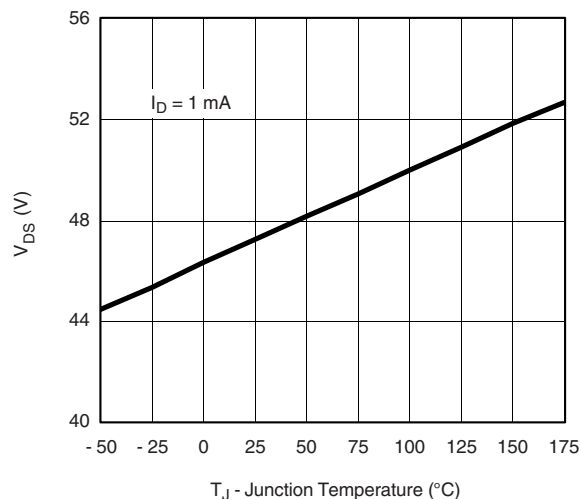
## TYPICAL CHARACTERISTICS $T_A = 25\text{ }^{\circ}\text{C}$ , unless otherwise noted



On-Resistance vs. Junction Temperature

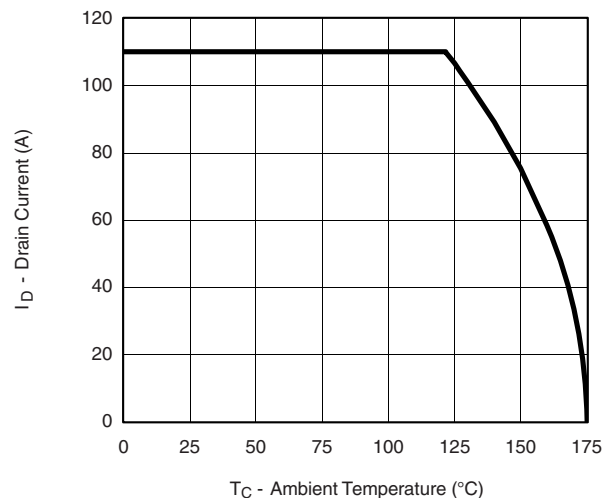


Source Drain Diode Forward Voltage

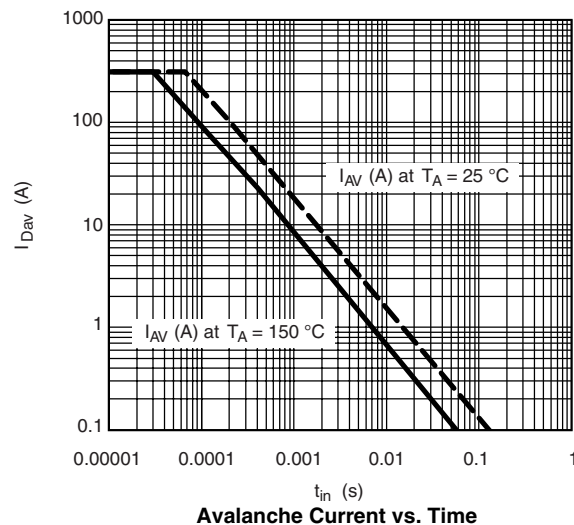


Drain Source Breakdown vs. Junction Temperature

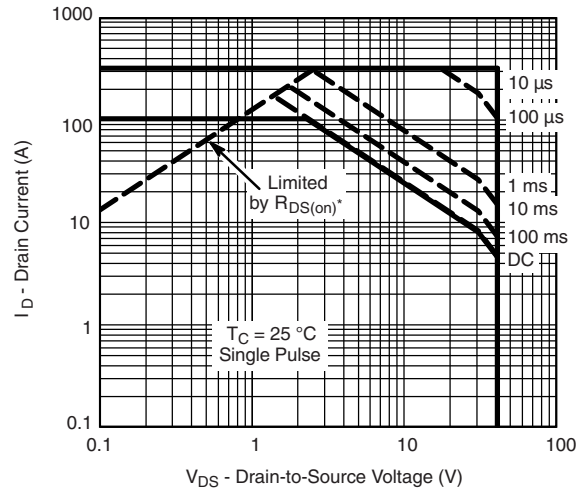
## THERMAL RATINGS $T_A = 25\text{ }^{\circ}\text{C}$ , unless otherwise noted



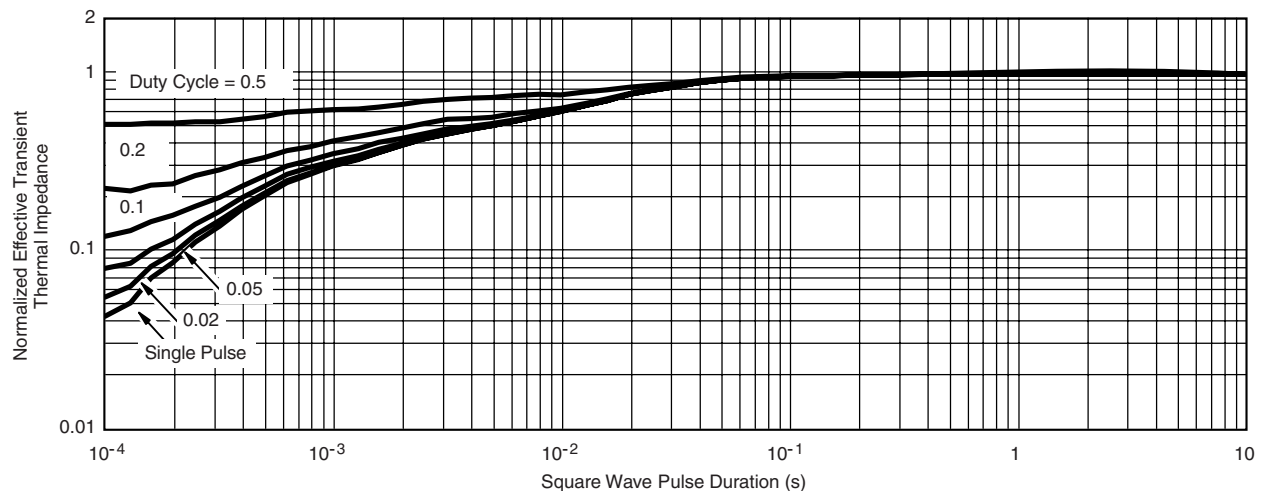
Maximum Drain Current vs. Ambient Temperature



Avalanche Current vs. Time

**THERMAL RATINGS**  $T_A = 25\text{ }^{\circ}\text{C}$ , unless otherwise noted


\*  $V_{GS} >$  minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

**Safe Operating Area**

**Normalized Thermal Transient Impedance, Junction-to-Case**
**Note**

The characteristics shown in the graph.

Normalized Transient Thermal Impedance Junction to Case ( $25\text{ }^{\circ}\text{C}$ ) is given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

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